

41st Electronics R&D and Manufacturing Technology Expo
NEPCON JAPAN × **ELECTRONIX** R&D JAPAN

Dates: Jan 18(Wed) - 20(Fri), 2012

Venue: Tokyo Big Sight, Japan

Organised by: Reed Exhibitions Japan, Ltd.

41st NEPCON JAPAN×ELECTRONIX R&D JAPAN Pre-Show Report
Asia's LARGEST Electronics Showcase with 1,960 Exhibitors!

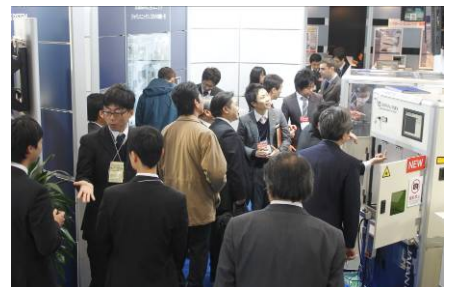
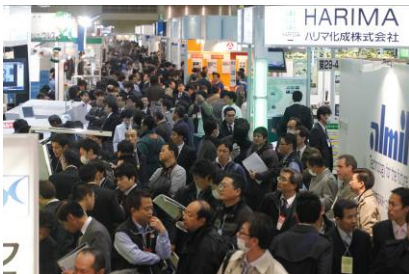


(Image of NEPCON JAPAN 2011)

NEPCON - **NATIONAL ELECTRONICS PACKAGING & PRODUCTION EXHIBITION** and **CONFERENCE** was launched in 1972 to enhance the Japanese electronics industry. Since its launch, NEPCON JAPAN has been evaluated as the world's leading electronics packaging show for over 30 years, and it has been growing together with the Japanese electronics industry. Since 2000, NEPCON JAPAN has changed its figure not only for production equipment but also to new related technologies such as IC packaging, PCB, electronic components and advanced materials. Now, NEPCON JAPAN has become the best place for everyone engaged in the electronics industry to experience the full lineups of products/technologies, from electronics R&D, design to manufacturing. In 2012, AUTOMOTIVE WORLD 2012 and LIGHTING JAPAN-4th LED/OLED Lighting Technology Expo will be concurrently held, which cover the hot topics of the main applications utilizing the electronics technologies, the automotive industry and the emerging LED/OLED lighting technologies. Furthermore, Organization for Small & Medium Enterprises and Regional Innovation, JAPAN(SME Support, JAPAN) will organize **FUTURE JAPAN** inside NEPCON JAPAN, where 70 SME who have unique and niche technologies will exhibit from all across Japan. With these shows, 41st NEPCON JAPAN x ELECTRONICS R&D JAPAN will be held in record-scale. **The future of electronics is ALL HERE!**

Exhibition Outline

Exhibition Title	41st NEPCON JAPAN x ELECTRONIX R&D JAPAN -41st INTERNEPCON JAPAN -29th ELECTROTEST JAPAN -13th IC PACKAGING TECHNOLOGY EXPO -13th INTERNATIONAL ELECTRONIC COMPONENTS TRADE SHOW(ELE TRADE 2012) -13th Printed Wiring Boards Expo (PWB EXPO) -3rd Advanced Electronic Materials Expo (MATERIAL JAPAN) -2nd Micro Fabrication/Fine Process Technology Expo (MicroTech JAPAN)
Dates	Jan 18 (Wed) -20(Fri), 2012
Venue	Tokyo Big Sight, Japan
Concurrent Events	Technical Conference
Concurrent Shows	AUTOMOTIVE WORLD 2012 LIGHTING JAPAN-4th LED/OLED Lighting Technology Expo
Total Exhibit Space	80,660m ² (Including Concurrent Shows)
Organised by	Reed Exhibitions Japan Ltd.



(Image of NEPCON JAPAN 2011)

Seminar Information

NEPCON JAPAN Show Management prepares technical seminars as concurrent events of the exhibition. In 2012, the show management has the honor to invite a total number of 185 industry leaders and VIPs to give speech on many of the hottest topics and the scale of the conference is also Asia's largest as for electronics related areas (including the seminar sessions for concurrent shows).

Keynote Sessions

English

Korean

Chinese

Japanese

[INJ-K] Industry Leaders' View: Strength of "Japan's Manufacturing Technologies"

Perspective Direction for Electronic System View
from Super High Band Communication



Kanji Otsuka
Emeritus Professor, Advisor
Collaborative Research Center of
Meisei University

Fujitsu's Technology that Developed the "K Computer"



Hideyuki Saso
Corporate Senior Executive Vice President
Fujitsu Ltd.

[PWB-K] Top Manufacturers Reveal their Strategies and Future Visions

BMW i-products and Services for Urban Mobility



Bernhard Blaettel
Director, Project Mobility Services
BMW AG

Evolution of Mobile Data Devices



Shigeyoshi Shimotsuji
Chief Technology Executive
Toshiba Corp.,
Digital Products & Services Company

[ICP-K] Future Outlook of Semiconductor Business -Keys to Enhance Electronics Industry-

Evolution of Semiconductor:
For Future Society and New User Experience



Tsuyoshi Abe
Director and Vice President,
and General Manager of Technology &
Manufacturing Group
Intel K.K.

Amkor Strategy for Packaging Technology



Choon-Heung Lee
Corporate Vice President, Head of Corp.
Technology HQ
Amkor Technology Korea, Inc.

Other Sessions

ALL the sessions are BILINGUAL

English

Japanese

Find topics of your interest from the full line-up.

Market Trends

**Smartphones &
Latest Mobile Devices**

**Cutting-edge
Material Technologies**

Latest trends/technologies
on **Mounting**

Latest trends/technologies
on **PWB/PCB**

Latest trends/technologies
on **IC Packaging**

For more details about technical seminar, visit >>>

<http://www.nepcon.jp/en/seminar/>

Contact information

NEPCON JAPAN Show Management, Reed Exhibitions Japan Ltd.
TEL: +81-3-3349-8502 FAX: +81-3-3349-4900
Attn: Kyoko NAGAKUSA(Ms), Sangmi JONG(Ms), Yuki OHMICHII(Ms), Lan GE(Ms)
E-mail: inw-pr@reedexpo.co.jp
Website: www.nepconjapan.jp/en/